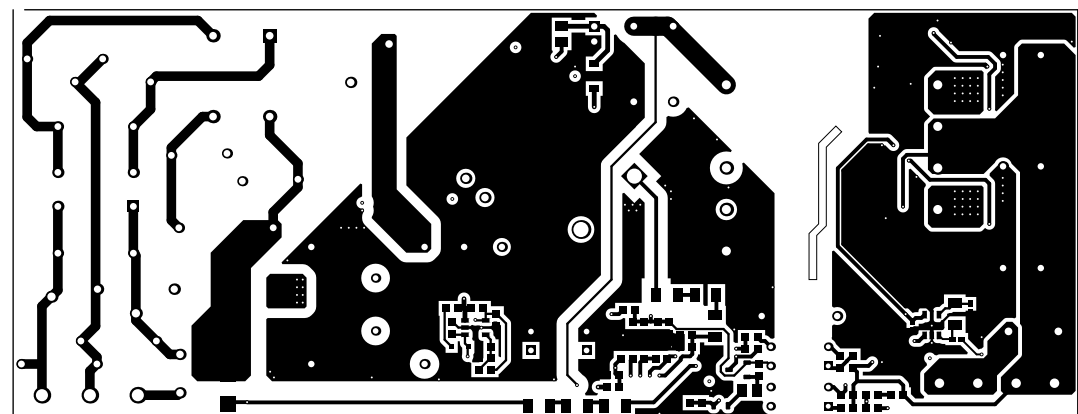
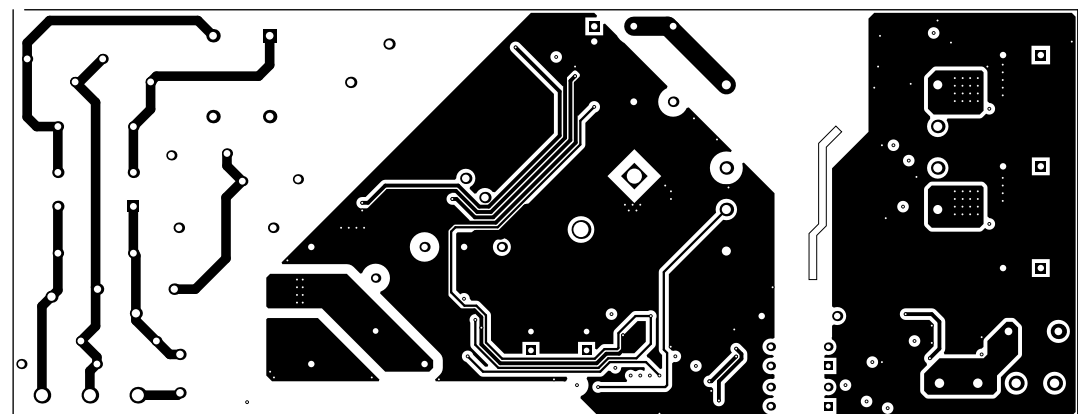


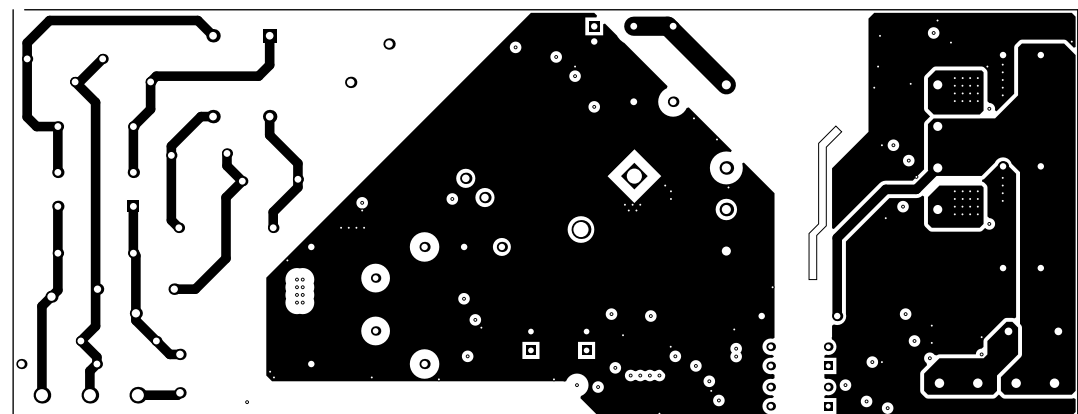
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 10/12/2017 10:04:48 AM	TEXAS INSTRUMENTS	



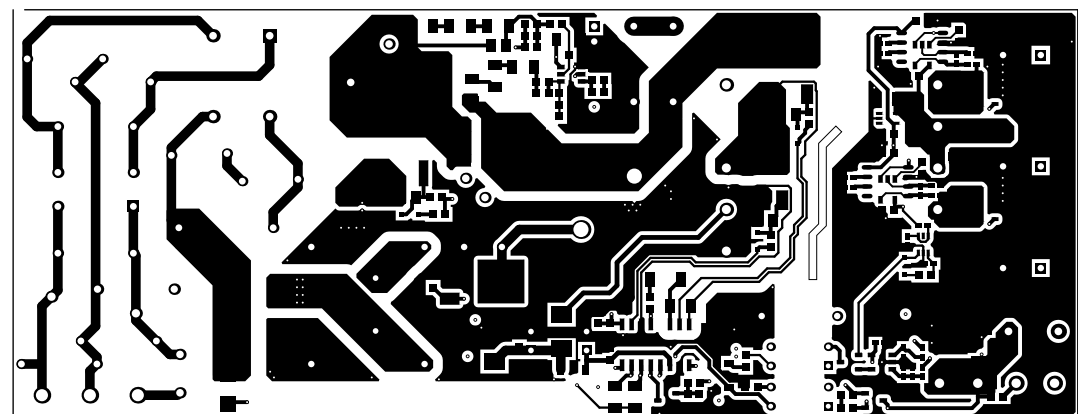
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 10/12/2017 10:04:49 AM	TEXAS INSTRUMENTS	



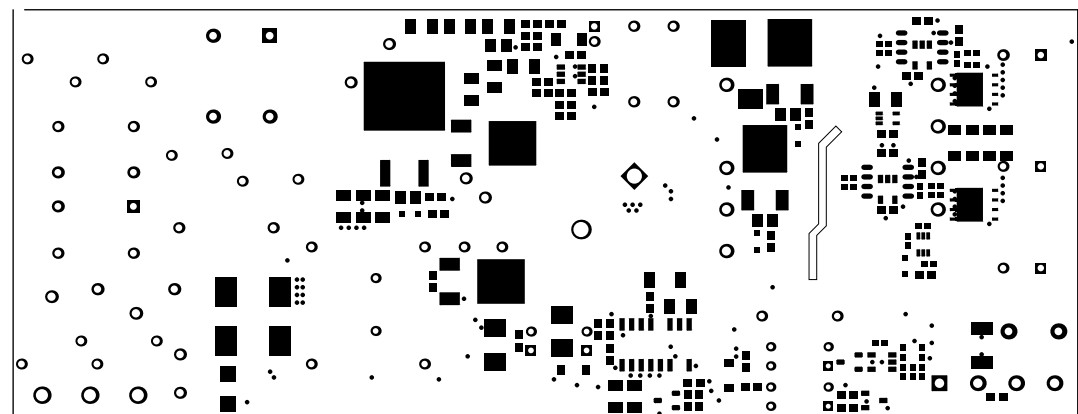
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 10/12/2017 10:04:51 AM	TEXAS INSTRUMENTS	



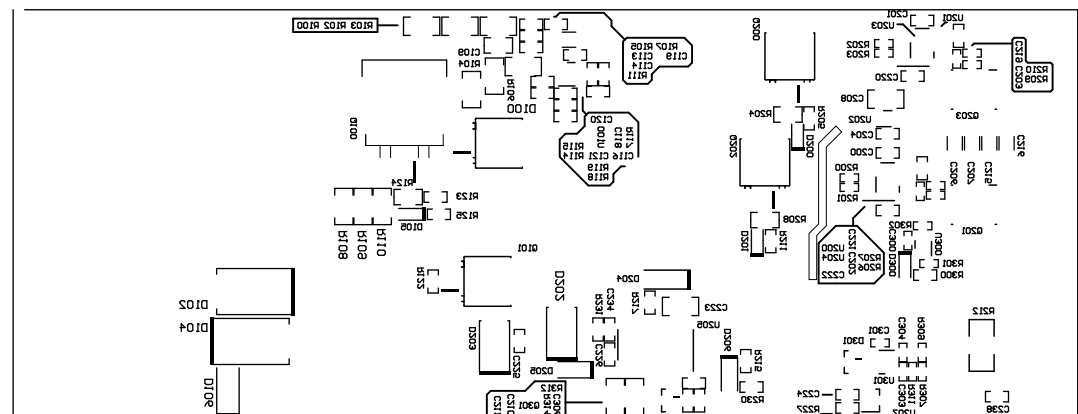
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 10/12/2017 10:04:53 AM	TEXAS INSTRUMENTS	



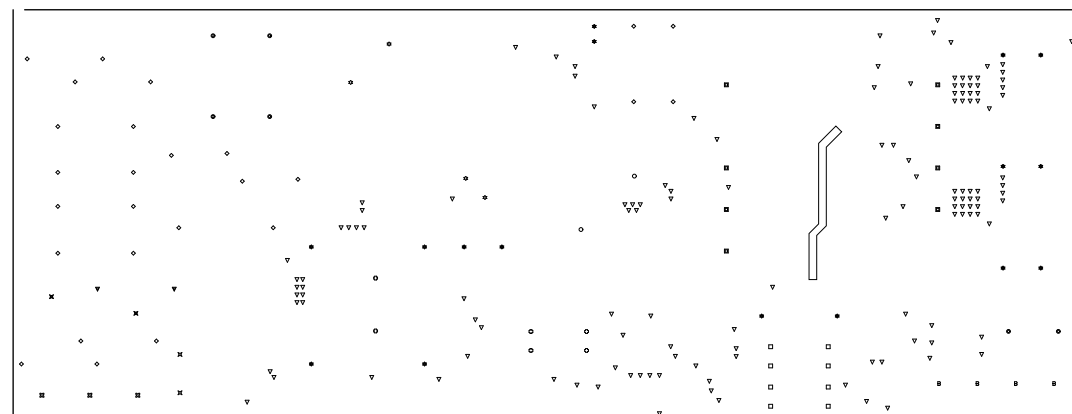
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 10/12/2017 10:04:54 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/12/2017 10:04:56 AM	TEXAS INSTRUMENTS	

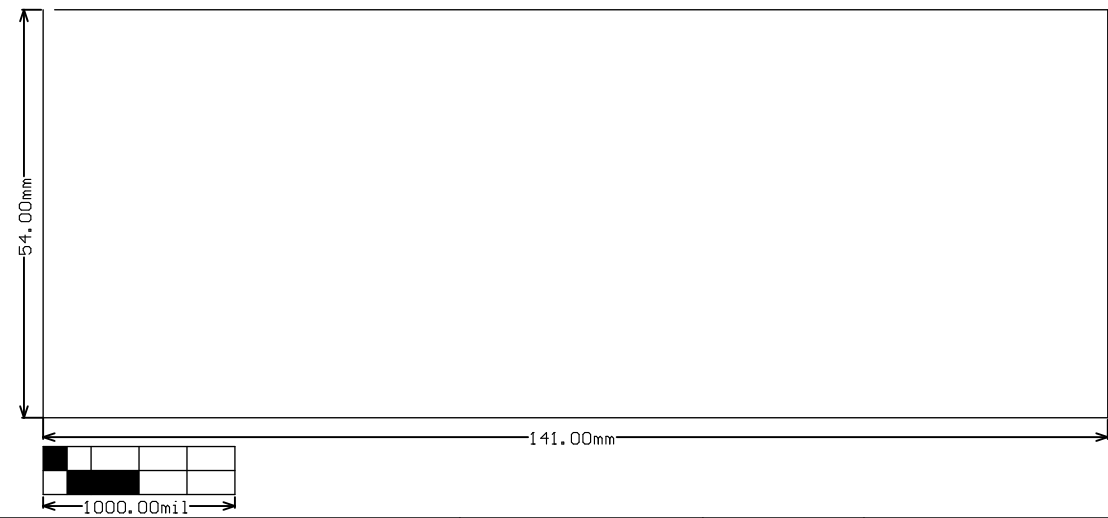


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 10/12/2017 10:04:59 AM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	133	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	±0.18mil
□	8	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
✱	16	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
◇	26	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	38.00mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
✱	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	8	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
	222 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 10/12/2017 10:05:00 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21098	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 10/12/2017 10:05:02 AM	TEXAS INSTRUMENTS	

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